

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) An IC card comprising:

a semiconductor device having a semiconductor chip at least partially sealed with a first sealing portion made of a thermosetting resin material and mounted over a front surface of a wiring substrate, and having, over a ~~first-rear~~ surface of the wiring substrate, an external connection terminal electrically connected to the semiconductor chip;

a case, covering the first sealing portion and the front surface of the wiring substrate, which is made of a thermoplastic resin material and on which the semiconductor device is loaded; and

a second sealing portion which is made of a thermoplastic resin material bonded to ~~said the~~ case, the second sealing portion covering the rear surface of the wiring substrate so as to seal ~~and sealing~~ the semiconductor device and ~~so as to~~ expose the external connection terminal, thereby integrating the semiconductor device with the case.

Claims 2 and 3 (canceled)

4. (currently amended) An IC card according to Claim [[2]] 1, wherein the semiconductor device has a connecting member for electrically connecting an ~~the~~ interconnect of the wiring substrate with the semiconductor chip, and the first sealing portion covers the connecting member.

Claim 5 (canceled)

6. (currently amended) An IC card according to Claim 1, wherein the second sealing portion is formed to cover a region, other than the external connection terminal, of the rear first ~~surface~~ of the wiring substrate ~~semiconductor~~ device.

7. (previously presented) An IC card according to Claim 1, wherein the case and the second sealing portion are made of the same material.

8. (previously presented) An IC card according to Claim 1, wherein the second sealing portion is welded to an interface portion of the case.

9. (currently amended) An IC card according to Claim 1, wherein the rear first-surface of the wiring substrate ~~semiconductor device~~ has a projecting portion, the external connection terminal is formed over the projecting portion of the rear first-surface, and the second sealing portion is formed to cover a region, other than the projecting portion, of the rear first-surface.

10. (previously presented) An IC card according to Claim 1, wherein the first sealing portion is made of an epoxy resin containing a silica filler.

11. (previously presented) An IC card according to Claim 1,

wherein the semiconductor device further comprises:
a die pad portion, the semiconductor chip being disposed over the die pad portion; and

a lead portion electrically connected to the semiconductor chip; and

wherein the first sealing portion covers the die pad portion, the semiconductor chip and the lead portion and exposes, as the external connection terminal, a part of the lead portion from an outer surface of the first sealing portion.

Claims 12-24 (canceled)

25. (currently amended) [[The]] An IC card according to[[of]] claim [[2]]1, wherein the second sealing portion has a portion molded to the case.

Claim 26 (canceled)

27. (currently amended) [[The]] An IC card according to[[of]] claim [[2]]1, wherein the second sealing portion has a first portion bonded to the case and a second portion bonded to the wiring substrate.

28. (currently amended) [[The]] An IC card according to[[of]] claim 27, wherein said first and second portions of the second sealing portion are unitary with each other.

29. (currently amended) [[The]] An IC card according to[[of]] claim 28, wherein said second portion of the second sealing portion is bonded to the rear[[first]] surface of the wiring substrate.

30. (currently amended) [[The]] An IC card according to[[of]] claim 28, wherein said second portion of the second

sealing portion is bonded to a peripheral edge of the wiring substrate.

31. (currently amended) ~~[[The]]~~ An IC card according to~~[[of]]~~ claim ~~[[2]]~~1, wherein the second sealing portion has a portion molded to the rear~~[[first]]~~ surface of the wiring substrate and a portion molded to a peripheral edge of the wiring substrate.

32. (new) An IC card comprising:

a substrate having a front surface and a rear surface;

a semiconductor chip mounted over the front surface of the substrate;

a first sealing portion formed of a thermosetting resin material and covering the semiconductor chip and a portion of the front surface adjacent to the semiconductor chip;

a plurality of external connection terminals arranged over the rear surface of the substrate;

a second sealing portion formed of a thermoplastic resin material and covering the rear

surface of the substrate such that the plurality of external connection terminals are exposed; and a case covering the first sealing portion and formed of a thermoplastic resin to which the second sealing portion adheres.

33. (New) An IC card according to Claim 32, wherein the first sealing portion is formed of an epoxy resin, and

wherein each of the second sealing portion and the case is formed with a material selected from the group consisting of a polycarbonate, ABS (acrylonitrile butadiene styrene resin), PBT (polybutylene terephthalate), PPE (polyphenylene ether), nylon, LCP (liquid crystal polymer), PET (polyethylene terephthalate), and mixtures thereof.

34. (New) An IC card according to Claim 32, wherein the second sealing portion has a lower content of glass filler than the first sealing portion.

35. (New) An IC card according to Claim 32, wherein the case has a lower content of glass filler than the first sealing portion.

36. (New) An IC card according to Claim 32, wherein part of the second sealing portion is arranged between the plurality of external connection terminals.

37. (New) An IC card according to Claim 32, wherein a rear surface of the case has a recessed portion, and

wherein the first sealing portion and the substrate are disposed in the recessed portion.

38. (New) An IC card according to Claim 37, wherein no adhesive is disposed between any of the first sealing portion, the substrate and the recessed portion.

39. (New) An IC card according to Claim 32, comprising a plurality of semiconductor chips mounted over the front surface of the substrate.

40. (New) An IC card according to Claim 39, wherein the plurality of semiconductor chips includes a flash memory chip and a controller chip for the flash memory chip.

41. (New) An IC card comprising:

an IC body having a front surface and a rear surface, the IC body including a substrate, a semiconductor chip, a plurality of external connection terminals and a first sealing portion formed of a first material and covering the semiconductor chip and a portion of the front surface adjacent to the semiconductor chip;

a second sealing portion covering the rear surface of the IC body such that the plurality of external connection terminals are exposed, the second sealing portion being formed of a second material different from the first material; and

a case receiving the IC body and formed of the second material, and to which the second sealing portion is welded.

42. (New) An IC card according to Claim 41, wherein the first material is an epoxy resin, and

wherein the second material is formed with a material selected from the group consisting of a polycarbonate, ABS (acrylonitrile butadiene styrene resin), PBT (polybutylene terephthalate), PPE (polyphenylene ether), nylon, LCP (liquid crystal polymer), PET (polyethylene terephthalate), and mixtures thereof.

43. (New) An IC card according to Claim 41, wherein the second material has a lower content of glass filler than the first material.

44. (New) An IC card according to Claim 41, wherein part of the second sealing portion is arranged between the plurality of external connection terminals.

45. (New) An IC card according to Claim 41, wherein a rear surface of the case has a recessed portion, and

wherein the IC body is disposed in the recessed portion.

46. (New) An IC card according to Claim 45, wherein no adhesive exists between the IC body and the recessed portion.

47. (New) An IC card according to Claim 41, wherein the IC body includes a plurality of semiconductor chips.

48. (New) An IC card according to Claim 47, wherein the plurality of semiconductor chips includes a flash memory chip and a controller chip for the flash memory chip.

49. (New) An IC card comprising:

a substrate having a front surface and a rear surface;

a semiconductor chip mounted over the front surface of the substrate;

a first sealing portion formed of a first material and covering the semiconductor chip and a portion of the front surface adjacent to the semiconductor chip;

a plurality of external connection terminals arranged over the rear surface of the substrate;

a second sealing portion formed of a material different from the first material and having a first portion and a second portion, wherein the first portion covers the rear surface of the substrate such that the plurality of external connection terminals are exposed; and

a case formed of the second material and having a first portion and a second portion, wherein the first portion of the case covers the first sealing portion, and the second portion of the case is formed integrally with the second portion of the second sealing portion.

50. (New) An IC card according to Claim 49, wherein the second material has a lower content of glass filler than the first material.

51. (New) An IC card according to Claim 49, wherein a part of the second sealing portion is arranged between the plurality of external connection terminals.

52. (New) An IC card according to Claim 49,
wherein the rear surface of the case has a recessed
portion, and

wherein the first sealing portion is disposed in
the recessed portion.

53. (New) An IC card according to Claim 52,
wherein no adhesive exists between the first sealing
portion and the recessed portion.

54. (New) An IC card according to Claim 49,
comprising a plurality of semiconductor chips.

55. (New) An IC card according to Claim 54,
wherein the plurality of semiconductor chips
includes a flash memory chip and a controller chip
for the flash memory chip.